

# RV1S9209A

R08DS0218EJ0100 Rev.1.00 Mar 29,2021

LOW FORWARD-CURRENT(IF) TOTEM POLE OUTPUT TYPE HIGH CMR, IPM DRIVER, 5-PIN SSOP WITH 8.2mm CREEPAGE DISTANCE (LSSO5) PHOTOCOUPLER

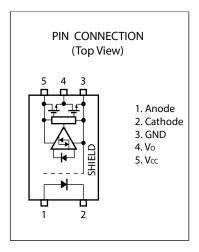
### DESCRIPTION

The RV1S9209A is an optical coupled high-speed, totem pole output (active high output type) isolator containing an AlGaAs LED on the input side and a photodiode and a signal processing circuit on the output side on one chip.

The RV1S9209A is specified high CMR and pulse width distortion with operating temperature. It is suitable for IPM (Intelligent Power Module) drive.

### **FEATURES**

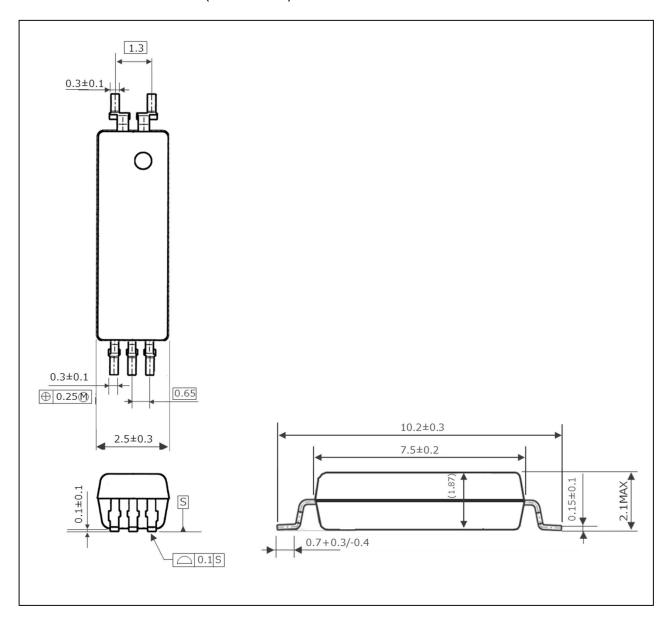
- Small and long creepage (8.2 mm MIN, LSSO5)
- Totem pole output (Active High Output Type)
- Pulse width distortion (|tplh tphl| = 80 ns MAX.)
- High common mode transient immunity (CM<sub>H</sub>, CM<sub>L</sub> = ± 50 kV/µs MIN.)
- Operating Ambient Temperature (125 °C MAX.)
- High isolation voltage (BV = 5 000 Vr.m.s.)
- Embossed tape product: RV1S9209ACCSP-10Yx#KC0: 3 500 pcs/reel
- Pb-Free product
- Safety standard
  - UL : UL1577, Double protection
  - CSA: CAN/CSA-C22.2 No.62368-1, Reinforced insulation
  - VDE: DIN EN 60747-5-5 (Option)



### **APPLICATIONS**

- IPM Driver
- General purpose inverter

# PACKAGE DIMENSIONS (UNIT: mm)

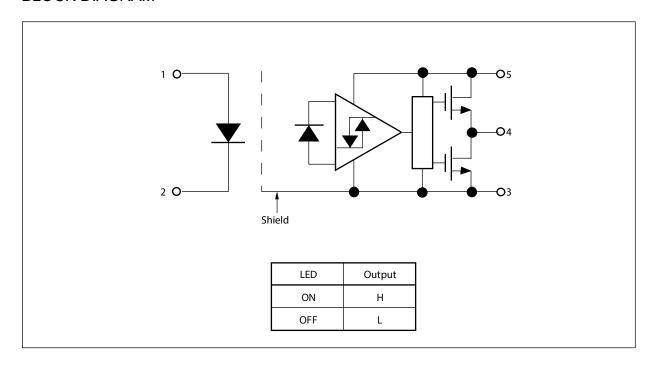


Weight: 0.075g (Typ.)

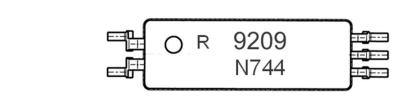
## PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	8.2 mm
Creepage Distance	8.2 mm
Isolation Distance	0.15 mm

### **BLOCK DIAGRAM**



## MARKING EXAMPLE



F	₹	An initial of "Renesas"		
92	09	Product Part Number *		
	)	No.1 pin Mark		
N744	N	Rank Code		
	744	Assembly Lot		
		7 Last one-digit of Assembly Year		
		44 Weekly Serial Code		

\*) Applicable type numbers listed below

RV1S 9209 ACCSP-10Yx

Marking type number. "RV1S" and "ACCSP-10Yx" are omitted from original type number.

### ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
RV1S9209ACCSP -10YC	RV1S9209ACCSP -10YC#SC0	Pb-Free and Halogen Free	20 pcs (Tape 20 pcs cut)	Standard products (UL, CSA approved)	RV1S9209A
	RV1S9209ACCSP -10YC#KC0	(Ni/Pd/Au)	Embossed Tape 3 500 pcs/reel		
RV1S9209ACCSP -10YV	RV1S9209ACCSP -10YV#SC0		20 pcs (Tape 20 pcs cut)	UL, CSA, DIN EN 60747-5-5	
	RV1S9209ACCSP -10YV#KC0		Embossed Tape 3 500 pcs/reel	approved	

Notes:\*1. For the application of the Safety Standard, following part number should be used.

# ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current	l <sub>F</sub>	20	mA
	Reverse Voltage	$V_{R}$	5	V
	Power Dissipation Derating	⊿P <sub>D</sub> /°C	1.2 (T <sub>A</sub> ≧ 110 °C)	mW/°C
	Power Dissipation	P <sub>D</sub>	45	mW
Detector	Supply Voltage	Vcc	−0.5 to +25	V
	Output Voltage	Vo	−0.5 to +25	V
	Output Current	lo	25	mA
	Power Dissipation Derating	⊿P <sub>C</sub> /°C	4.0 (T <sub>A</sub> ≥ 85 °C)	mW/°C
	Power Dissipation	Pc	250	mW
Isolation Voltage*1		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	-40 to +125	°C
Storage Temperature		$T_{stg}$	−55 to +150	°C

Notes: \*1. AC voltage for 1 minute at  $T_A$  = 25 °C, RH = 60 % between input and output. Pins 1-2 shorted together, 3-5 shorted together.

### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>CC</sub>	4.5	15	20	V
Forward Current (ON)	I <sub>F(ON)</sub>	5		10	mA
Forward Voltage (OFF)	$V_{F(OFF)}$	0		8.0	V
Operating Ambient Temperature	T <sub>A</sub>	-40		125	°C

### **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = -40 to +125  $^{\circ}$ C, V<sub>CC</sub> = 4.5 to 20 V, unless otherwise specified)

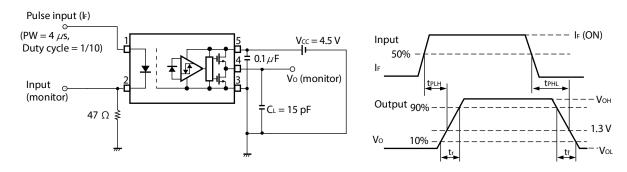
	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	VF	I <sub>F</sub> = 10 mA, T <sub>A</sub> = 25 °C	1.35	1.56	1.75	V
	Reverse Current	IR	V <sub>R</sub> = 3 V, T <sub>A</sub> = 25 °C			10	μA
	Input Capacitance	Ct	V <sub>F</sub> = 0 V, f = 1 MHz, T <sub>A</sub> = 25 °C		30		pF
Detector	High Level Supply Current	Іссн	V <sub>CC</sub> = 4.5 V, I <sub>F</sub> = 5 mA		1.0	3	mA
			V <sub>CC</sub> = 20 V, I <sub>F</sub> = 5 mA		1.6	3	
	Low Level Supply Current	Iccl	$V_{CC} = 4.5 \text{ V}, I_F = 0 \text{ mA}$		1.2	3	mA
			V <sub>CC</sub> = 20 V, I <sub>F</sub> = 0 mA		1.8	3	
	High Level Output Voltage	Vон	$V_{CC} = 4.5 \text{ V}, I_0 = -2.6 \text{ mA},$ $I_F = 5 \text{ mA}$	2.7	3.1		V
			$V_{CC} = 20 \text{ V}, I_{O} = -2.6 \text{ mA},$ $I_{F} = 5 \text{ mA}$	17.4	18.6		
	Low Level Output Voltage *2	Vol	I <sub>O</sub> = 3.5 mA, I <sub>F</sub> = 0 mA		0.25	0.6	V
	High Level Output Short *3 Circuit Current	Іоѕн	$V_{CC} = 4.5 \text{ V}, V_{O} = \text{GND},$ $I_{F} = 5 \text{ mA}$	-7	-45		mA
	Low Level Output Short *3 Circuit Current	losu	$V_{CC} = V_{O} = 4.5 \text{ V}, V_{F} = 0 \text{ V}$	7	34		mA
Coupled	Threshold Input Current	IFLH	$V_{CC} = 4.5 \text{ V}, V_O > 2.7 \text{ V},$ $I_O = -2.6 \text{ mA}$		1.6	3.8	mA
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1kVDC, RH = 60 %, T <sub>A</sub> = 25 °C	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1MHz, T <sub>A</sub> = 25 °C		0.6		pF
	Propagation Delay Time $(H \rightarrow L)^{*4}$	t <sub>PHL</sub>	$C_L$ = 15 pF, $I_F$ = 5 $\rightarrow$ 0 mA, $V_{THHL}$ = 1.3 $V$		108	200	ns
	Propagation Delay Time $(L \rightarrow H)^{*4}$	tрLН	$C_L$ = 15 pF, $I_F$ = 0 $\rightarrow$ 5 mA, $V_{THLH}$ = 1.3 $V$		121	200	
	Pulse Width Distortion (PWD)	tpln-tphl	$C_L = 15 \text{ pF}, I_F = 5 \leftrightarrow 0 \text{ mA}$		13	80	ns
	Propagation Delay Difference Between Any Two Parts (PDD)					100	
	Rise Time (10-90%)*4	tr	$C_L = 15 \text{ pF}, I_F = 0 \rightarrow 5 \text{ mA}$		25		ns
	Fall Time (90-10%)*4	t <sub>f</sub>	$C_L$ = 15 pF, $I_F$ = 5 $\rightarrow$ 0 mA		5		
	Common Mode Transient Immunity at High Level Output*5	CM <sub>H</sub>	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25 °C, I <sub>F</sub> = 5 mA,  V <sub>CM</sub>   = 1.5 kV	50			kV/μs
	Common Mode Transient Immunity at Low Level Output*5	CM <sub>L</sub>	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25 °C, I <sub>F</sub> =0 mA,  V <sub>CM</sub>   = 1.5 kV	50			

Notes: \*1. Typical values at T<sub>A</sub> = 25 °C

<sup>\*2.</sup> Because  $V_0$  of 2.4 V may be output when the LED current is not input and when output supply of  $V_{CC}$  = 4.5 V or less, it is important to confirm the characteristics (operation with the power supply on and off) during design, before using this device.

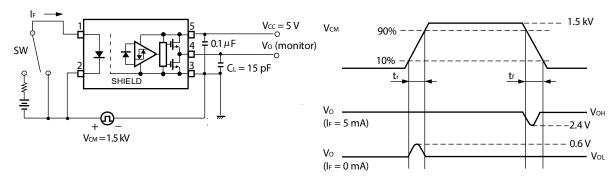
<sup>\*3.</sup> Duration of output short circuit time should not exceed 10 ms.

### \*4. Test circuit for propagation delay time



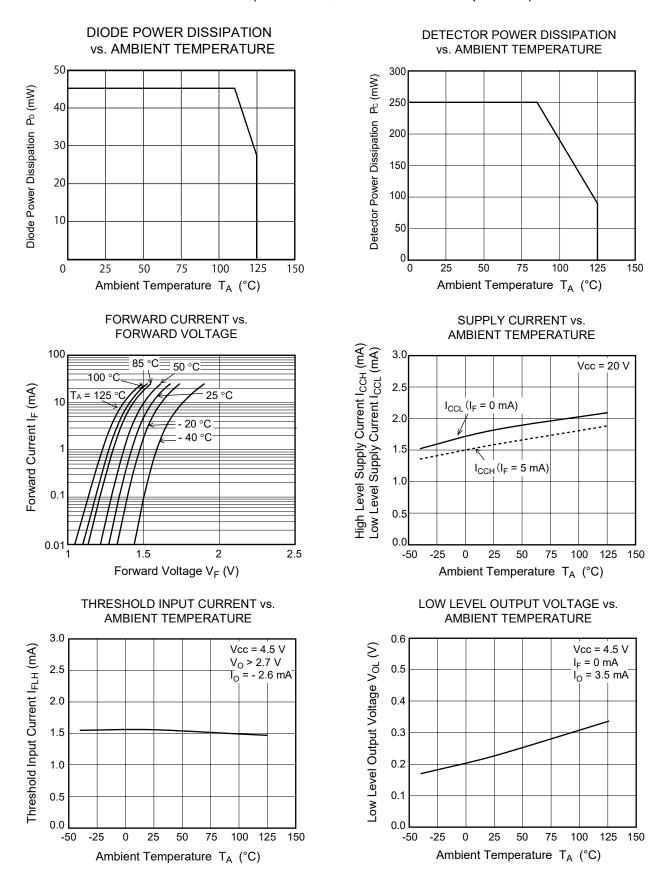
Remark C<sub>L</sub> includes probe and stray wiring capacitance.

### \*5. Test circuit for common mode transient immunity



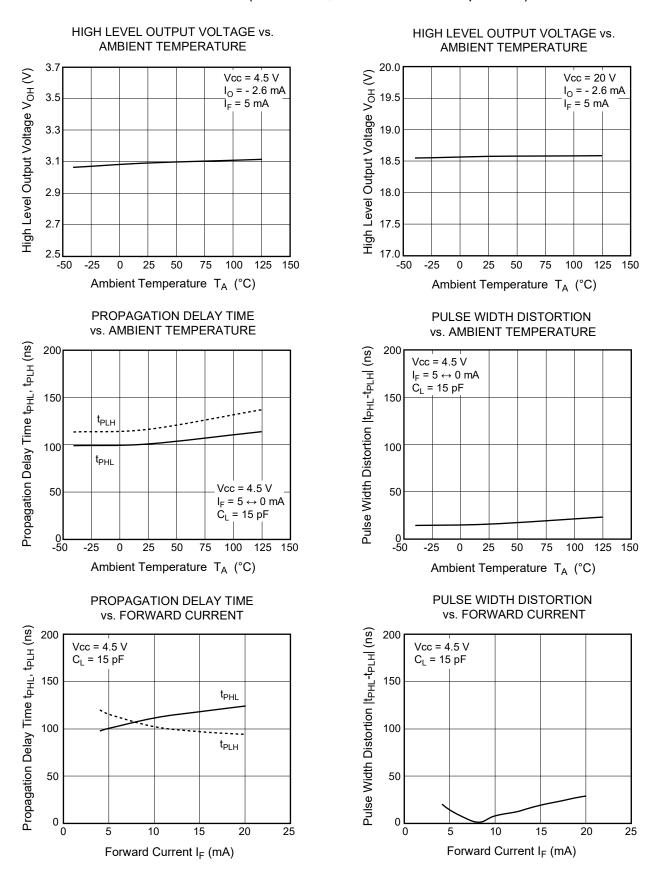
Remark CL includes probe and stray wiring capacitance.

## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise specified)



**Remark** The graphs indicate nominal characteristics.

## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise specified)

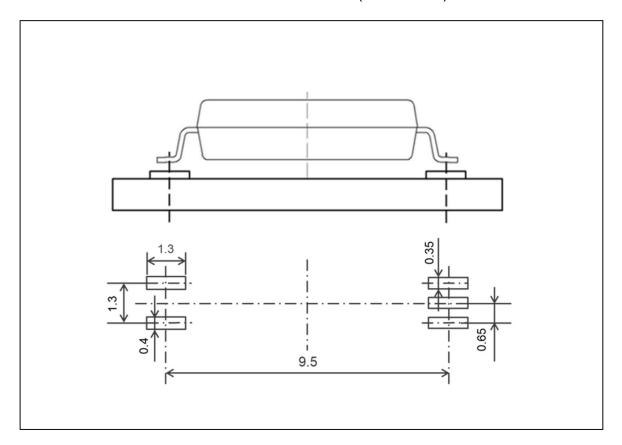


**Remark** The graphs indicate nominal characteristics.

## TAPING SPECIFICATIONS (UNIT: mm)

# **Taping Direction** Direction of feed Unit: mm Outline and Dimensions (Tape) Φ1.5 <sup>+0.1</sup><sub>-0</sub> 2±0.1 (14.25)0.4±0.1 Ф1.5 <sup>+0.1</sup> 4±0.1 Unit: mm Outline and Dimensions (Reel) 2.0±0.5 φ13.0±0.2 φ330±2.0 φ100±1.0 17.5±1.0 21.5±1.0 Packing: 3 500 pcs/reel

# RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

### NOTES ON HANDLING

- 1. Recommended soldering conditions
  - (1) Infrared reflow soldering

Peak reflow temperature 260°C or below (package surface temperature)

Time of peak reflow temperature
 Time of temperature higher than 220°C
 Time to probably temperature from 130 to 180°C

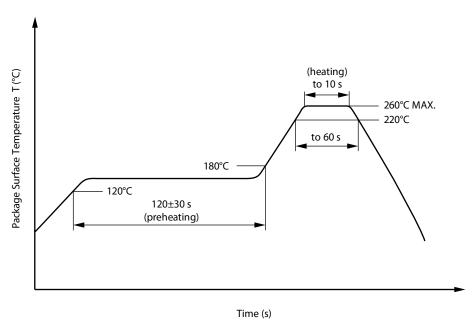
Time to preheat temperature from 120 to 180°C
 Number of reflows
 Three

Number of reflows Three
Flux Rosin flux containing small amount of chlorine (The

flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

Recommended Temperature Profile of Infrared Reflow



## (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

Time 10 seconds or less

Preheating conditions 120°C or below (package surface temperature)

• Number of times One (Allowed to be dipped in solder including plastic mold portion.)

Flux Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

Peak Temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 100°C

### (4) Cautions

· Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

• Do not use fixing agents or coatings containing halogen-based substances.

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

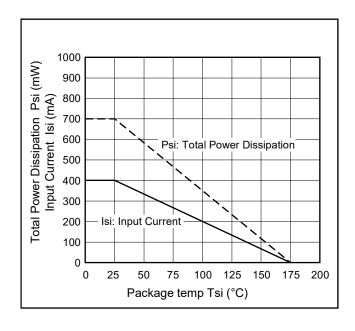
### **USAGE CAUTIONS**

- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than 0.1  $\mu$ F is used between V<sub>CC</sub> and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.

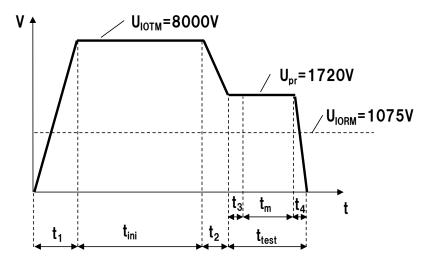
## SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/125/21	
Dielectric strength			
maximum operating isolation voltage	UIORM	1 075	$V_{\text{peak}}$
Test voltage (partial discharge test, procedure a for type test and random	$U_pr$	1 720	$V_{peak}$
test)			
$U_{pr} = 1.6 \times U_{IORM.}, P_d < 5 pC$			
Test voltage (partial discharge test, procedure b for all devices)	Upr	2 016	$V_{peak}$
$U_{pr} = 1.875 \times U_{IORM.}$ , $P_d < 5 pC$	Opr	2010	v peak
Highest permissible overvoltage	U <sub>ІОТМ</sub>	8 000	$V_{peak}$
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	400	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		П	
Storage temperature range	T <sub>stg</sub>	-55 <b>~</b> +150	°C
Operating temperature range	T <sub>A</sub>	-40~+125	°C
Isolation resistance, minimum value			
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> = 25°C	Ris MIN.	10 <sup>12</sup>	Ω
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> MAX. at least 100°C	Ris MIN.	10 <sup>11</sup>	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal			
derating curve)			
Package temperature	Tsi	175	°C
Current (input current I⊧, Psi = 0)	Isi	400	mA
Power (output or total power dissipation)	Psi	700	mW
Isolation resistanceV <sub>IO</sub> = 500 V dc at T <sub>A</sub> = Tsi	Ris MIN.	10 <sup>9</sup>	Ω

# Dependence of maximum safety ratings with package temperature



#### 



$$t_1, t_2 = 1$$
 to 10 sec

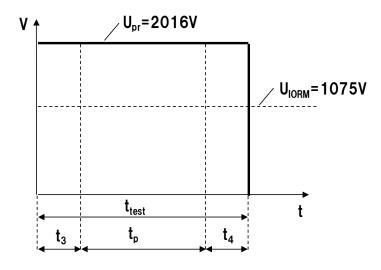
$$t_3, t_4 = 1 \text{ sec}$$

 $t_{m \, (PARTIAL \, DISCHARGE)} = 10 \, sec$ 

 $t_{test}$ =12 sec

t<sub>ini</sub>=60 sec

## Method b) Non-destructive Test, 100% Production Test



$$t_3, t_4 = 0.1 \text{ sec}$$

$$t_{test}$$
=1.2 sec

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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(Rev.5.0-1 October 2020)

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